

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (canceled).

2. (previously presented): The method of claim 5, wherein the final polymer constituting the pressure-sensitive adhesive is an acrylic polymer obtained by polymerizing one or more monomers in liquid or supercritical carbon dioxide.

Claims 3 and 4. (canceled).

5. (currently amended): A semiconductor wafer processing method, comprising adhering a removable pressure-sensitive adhesive sheet ~~which comprises wherein~~ a pressure-sensitive adhesive layer comprises comprising, as a final polymer constituting a pressure-sensitive adhesive, ~~a final polymer~~ in which the final polymer content of low-molecular components having a molecular weight of 105 or lower is 10% by weight or lower, and the final polymer has a weight average molecular weight of 930,000 to 2,100,000, to a front or back surface of the wafer, and processing the wafer.